

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A ~~substrate with a microstructure~~ semiconductor device ~~formed thereon, the substrate comprising:~~

~~a lower substrate supporting an upper substrate;~~

a buffer layer having a plurality of spaced apart shapes formed on, and extending above, a planar upper ~~an upper surface of the~~ of a lower substrate; ~~to have a plurality of shapes with air gaps defined between each of said shapes and spaced apart from each other at regular intervals; and~~

an adhesive layer formed directly on the plurality of spaced apart shapes; and

an upper substrate removably adhered to an upper surface of the adhesive layer; ~~between the upper substrate and the buffer layer so that the upper substrate is removably adhered to the lower substrate by the adhesive layer and the buffer layer;~~

wherein, the upper substrate has a substantially higher flexibility than that of the lower substrate, and on which a semiconductor device is formed.

2. (Currently Amended) The ~~substrate device~~ as claimed in claim 1, wherein the lower substrate is made of at least one of Si, SiO₂, Al₂O₃, copper, copper alloy, aluminum, aluminum alloy, and glass.

3. **(Currently Amended)** The ~~substrate~~device as claimed in claim 1, wherein the buffer layer is made of at least one of SiO₂, Al₂O₃, AlON, SiON, Si₃N₄, AlN, SOG (spin-on-glass), photosensitive material, Cu, Cu alloy, Al, and Al alloy.

4. **(Currently Amended)** The ~~substrate~~device as claimed in claim 1, wherein the buffer layer is patterned and etched to form a plurality of shapes arranged in many rows or to form a plurality of shapes arranged in hexahedron or cylindrical islands, with stress relaxing non-enclosed air gaps being spaced apart from each other at regular intervals.

5. **(Currently Amended)** The ~~substrate~~device as claimed in claim 1, wherein the adhesive layer is made of any one of a double sided tape, a liquid adhesive, and organic film, to withstand a hot process of more than 100.degree. C.

6. **(Currently Amended)** The ~~substrate~~device as claimed in claim 1, wherein the upper substrate is made of any one of plastic, stainless steel, copper, copper alloy, aluminum, aluminum alloy, silicon, and glass.

7-14. (Canceled).